

3.0x2.0 mm SMD CHIP LED LAMP

AA3020MGC

MEGAGREEN

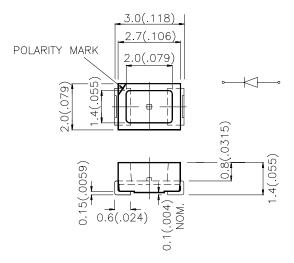
Features

- •3.0MM X 2.0MM, 1.4MM HIGH, ONLY MINIMUM SPACE REQUIRED.
- •SUITABLE FOR COMPACT OPTOELECTRONIC APPLICATIONS.
- •LOW POWER CONSUMPTION.
- •EMBOSSED TAPING.
- •PACKAGE: 2000PCS/REEL.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25 (0.01\mbox{"})$ unless otherwise noted.
- 3. Lead spacing is measured where the lead emerge package.
- 4. Specifications are subject to change without notice.

SPEC NO: CDA0415 APPROVED:J.LU REV NO: V.1 CHECKED: DATE: OCT/27/2001 DRAWN:Y.F.XU PAGE: 1 OF 4



Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20 mA		Viewing Angle
			Min.	Тур.	201/2
AA3020MGC	MEGA GREEN (InGaAIP)	WATER CLEAR	40	80	90°

Note:

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Mega Green	574		nm	IF=20mA
λD	Dominate Wavelength	Mega Green	568		nm	IF=20mA
Δλ 1/2	Spectral Line Halfwidth	Mega Green	26		nm	IF=20mA
С	Capacitance	Mega Green	20		pF	VF=0V;f=1MHz
V _F	Forward Voltage	Mega Green	2.1	2.5	V	IF=20mA
I _R	Reverse Current	Mega Green		10	uA	VR = 5V

Absolute Maximum Ratings at T_A=25°C

Parameter	Mega Green	Units
Power dissipation	105	mW
DC Forward Current	30	mA
Peak Forward Current [1]	205	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

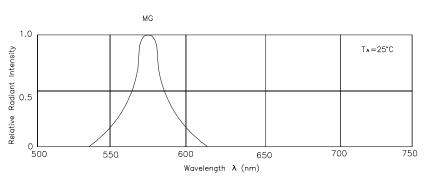
Note

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

SPEC NO: CDA0415 APPROVED:J.LU REV NO: V.1 CHECKED: DATE: OCT/27/2001 DRAWN:Y.F.XU PAGE: 2 OF 4

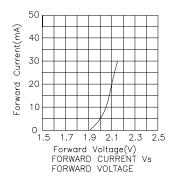
^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

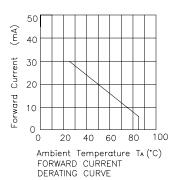


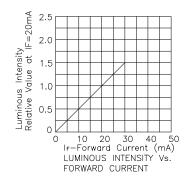


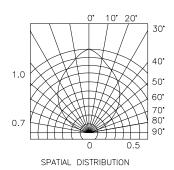
RELATIVE INTENSITY Vs. WAVELENGTH

Hyper Red AA3020MGC









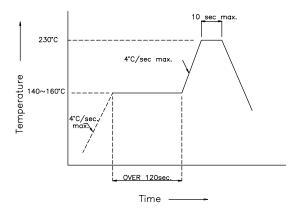
DATE: OCT/27/2001 DRAWN:Y.F.XU PAGE: 3 OF 4

Kingbright

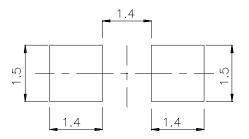
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SMT Reflow Soldering Instructions

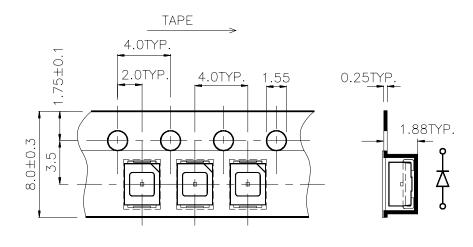
Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



Recommended Soldering Pattern (Units:mm)



Tape Specifications (Units:mm)



SPEC NO: CDA0415 APPROVED:J.LU REV NO: V.1 CHECKED: DATE: OCT/27/2001 DRAWN:Y.F.XU PAGE: 4 OF 4